

## Information for Lot 9 of ErP (Ecodesign)

This addendum addresses European Union (EU) Ecodesign requirements for servers and storage products. All data and ratings within this addendum are in reference only to the Supermicro product(s) in the manual. The below information conforms to requirements laid down in Annex II of the Commission Regulation 2019/424.

- 3(1)(a): See Section 1.1 of the system manual for the product type.
- 3(1)(b): See the title page and preface of the system manual for the trademark and manufacturer's address.
- 3(1)(c): See the title page of the system manual for product model number(s).
- 3(1)(d): See the serial number on the physical system to determine the year of manufacture.
- 3(1)(e-j): **PSU Efficiency and Power Factor Value (Table) (From 80 Plus report)**

<b>PSU Model #: PWS-2K63A-1R Watts: 2600W</b>	<b>PSU Efficiency</b>				<b>Power Factor</b>
<b>% of Rated Load</b>	<b>10 %</b>	<b>20 %</b>	<b>50 %</b>	<b>100 %</b>	<b>50 %</b>
Single Output (AC-DC)	93.52%	96.03%	96.21%	94.25%	0.99

### **System (EUT) Efficiency in Idle State Power (Table)**

<b>Representative Configurations</b>	<b>Measured Idle State Power (W)</b>	<b>Calculated Idle Power Allowance (W)</b>
High-End Performance Configuration	467.7	495.2
Typical Configuration	N/A	N/A
Low-End Performance Configuration	276.0	514.4

### **System (EUT) Efficiency in Active State Power (Table)**

<b>Representative Configurations</b>	<b>Active State Efficiency Score (Effserver)</b>	<b>Minimum Active State Efficiency for 2-Socket Server</b>
High-End Performance Configuration	30.8	9.5
Typical Configuration	N/A	
Low-End Performance Configuration	37.2	

3(1)(k): The operating condition class is **A2**.

Operating condition class	Dry bulb temp °C		Humidity range, non-condensing		Max dew point (°C)	Maximum rate of change (°C/hr)
	Allowable range	Recommended	Allowable range	Recommended range		
A1	15- 32	18-27	- 12 °C Dew Point (DP) and 8 % relative humidity (RH) to 17 °C DP and 80 % RH	- 9 °C DP to 15 °C DP and 60 % RH	17	5/20
A2	10-35	18-27	- 12 °C DP and 8 % RH to 21 °C DP and 80 %	Same as A1	21	5/20
A3	5-40	18-27	- 12 °C DP and 8 % RH to 24 °C DP and 85 %	Same as A1	24	5/20
A4	5-45	18-27	- 12 °C DP and 8 % RH to 24 °C DP and 90 %	Same as A1	24	5/20

3(1)(l): The idle state power at the higher boundary temperature of the operating conditions class is 551.89 W.

3(1)(m): The active state efficiency and performance is 30.8.

3(1)(n): There are two methods by which a user can securely delete data from this system. The user performing secure data deletion should be an IT professional.

The first is with a Unified Extensible Firmware Interface (UEFI) shell utility. This utility works on X10/X11/H11/H12/M11 motherboard series with onboard SATA/NVMe devices. Any user may access and download this utility through following link:  
[https://www.supermicro.com/about/policies/disclaimer.cfm?url=/wftp/utility/Lot9\\_Secure\\_Data\\_Deletion\\_UTILITY/](https://www.supermicro.com/about/policies/disclaimer.cfm?url=/wftp/utility/Lot9_Secure_Data_Deletion_UTILITY/)

Download the shell utility package and extract it to a USB flash drive, then plug the drive into the server for which secure data deletion is necessary. Then turn the system on. Navigate to the BIOS setup menu, then place the server system into the UEFI shell environment. Follow the instructions in the README file to invoke the utility and complete the deletion.

The second method is through the secure data deletion tool provided by the original manufacturer of the hard drive. This should be used in a scenario where the shell utility is not applicable. Each manufacturer should have the tool available on their website. If needed, please look on the hard drive label for the name of the manufacturer and model information.

3(1)(o): List of recommended combinations of blade servers with chassis: N/A.

3(1)(p): List of all current SKUs within this product family.

- SYS-2029GP-TR
- SYS-220GP-TNR

3(3)(a): There is no use of cobalt in batteries in this product.

The indicative weight range of neodymium in the HDD is 0.0 if manufactured by Western Digital, and is between 5-25 grams if manufactured by Seagate.

3(3)(b): Please see the disassembly instructions on the next page.

## Illustrated System Disassembly Instructions

*Please note: All the illustrations in the below disassembly instructions are for demonstration only. Components shown here may not match exactly with the components in your system.*

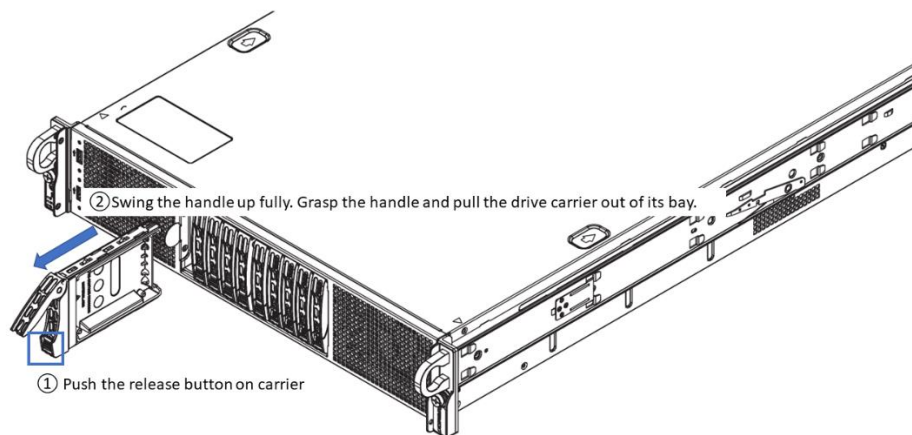
**CAUTION: Always power off the system and unplug the power cord(s) first before disassembling the system!**

### 1. Data Storage Devices

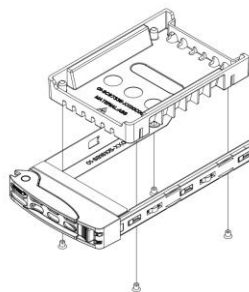
*Type and number of fastenings:* One (1) latch and four (4) PH2 screws.

*Tools required:* Screwdriver with PH2 bit.

*Procedure:* Push the release button on the carrier. Fully swing the handle up, then pull the drive carrier out of its bay.



Remove the drive from the carrier by unfastening the screws with a PH2 bit.



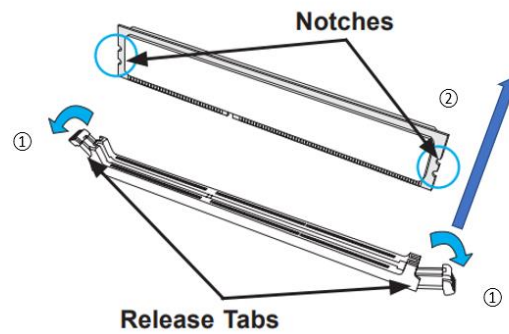
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## 2. Memory

Type and number of fastenings: Two (2) latches per memory module.

Tools required: None.

Procedure: Press both release tabs on the ends of the memory module to unlock it. Once the module is loosened, remove it from the memory slot.

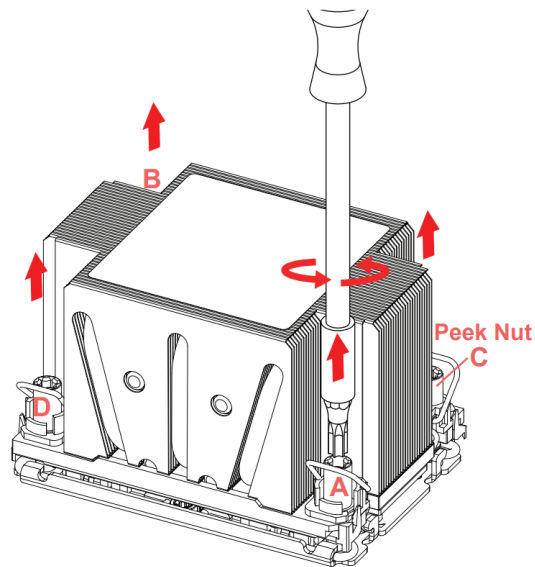


### 3. Processor

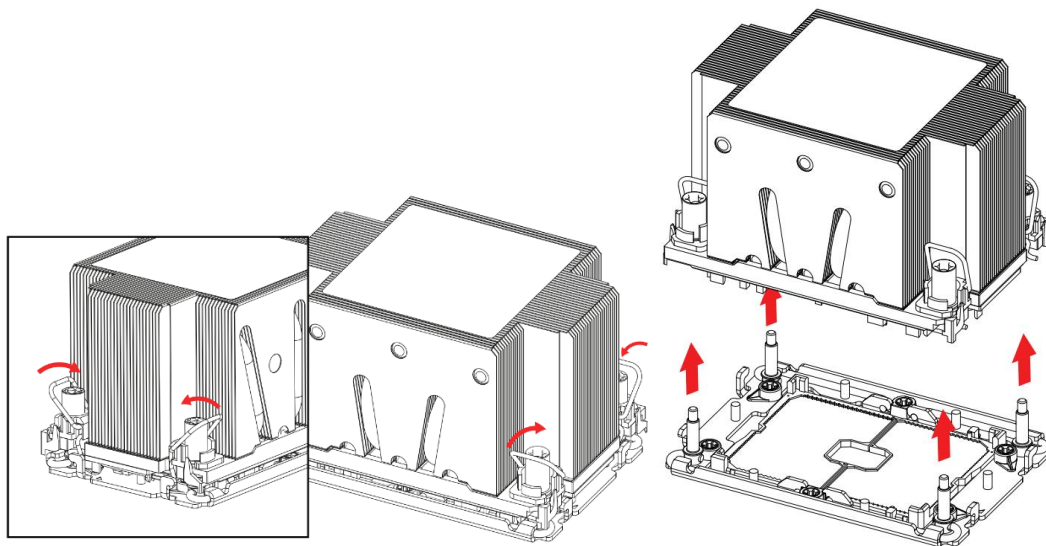
Type and number of fastenings: Four (4) T30 peek nuts.

Tools required: Screwdriver with T30 bit.

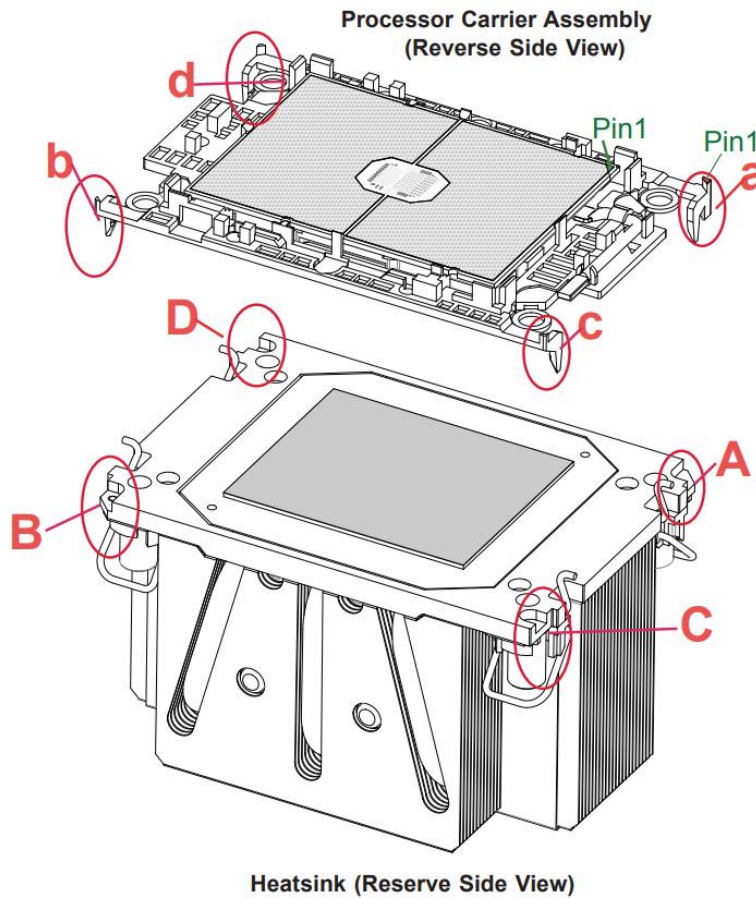
Procedure: Loosen the peek nuts on each corner of the heatsink in the sequence of A, B, C, then D, as marked in the illustration below.



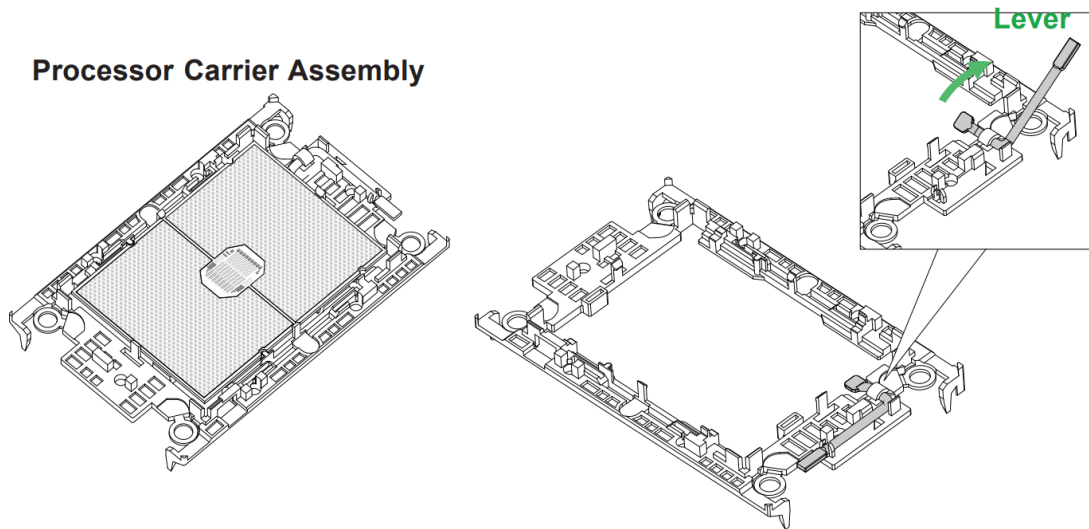
After loosening the peek nuts, unlatch the rotating wires in each corner by pressing the rotating wires inward. Lift the heatsink-carrier assembly upward to remove it from the processor socket.



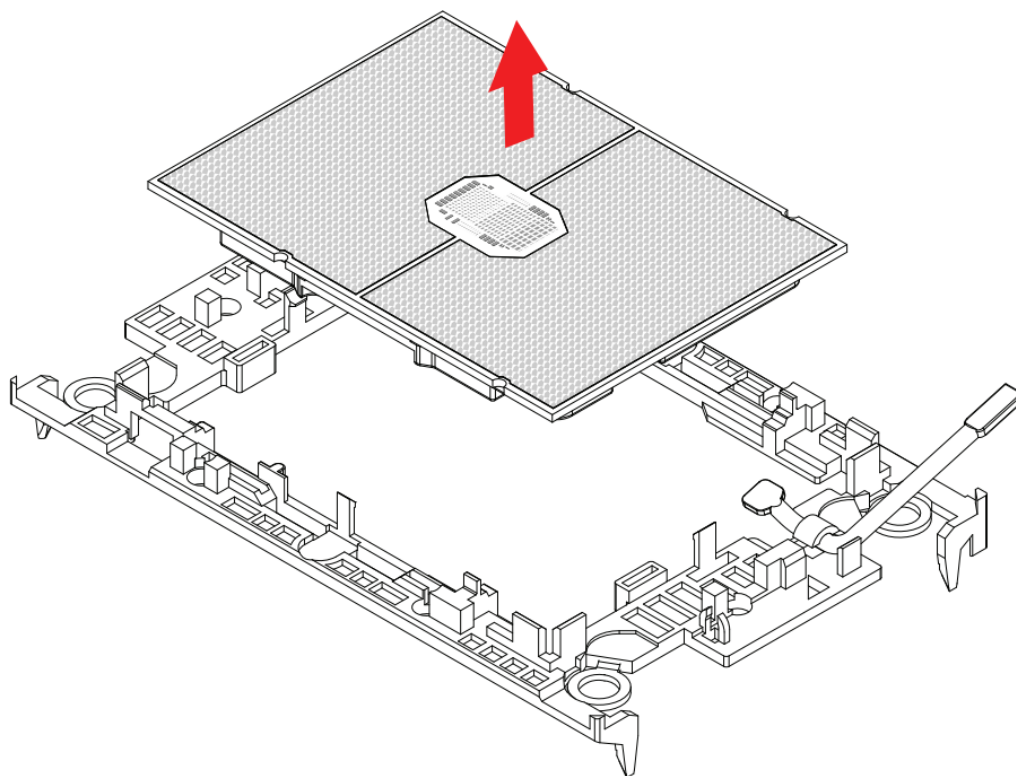
Turn the heatsink-carrier assembly over, as shown below. Remove the processor-carrier assembly from the heatsink by detaching the plastic clips (marked a, b, c, d) on the processor-carrier assembly.



Loosen the processor from the carrier by pushing the lever on the carrier upward, as shown.



Lift the processor off the carrier.



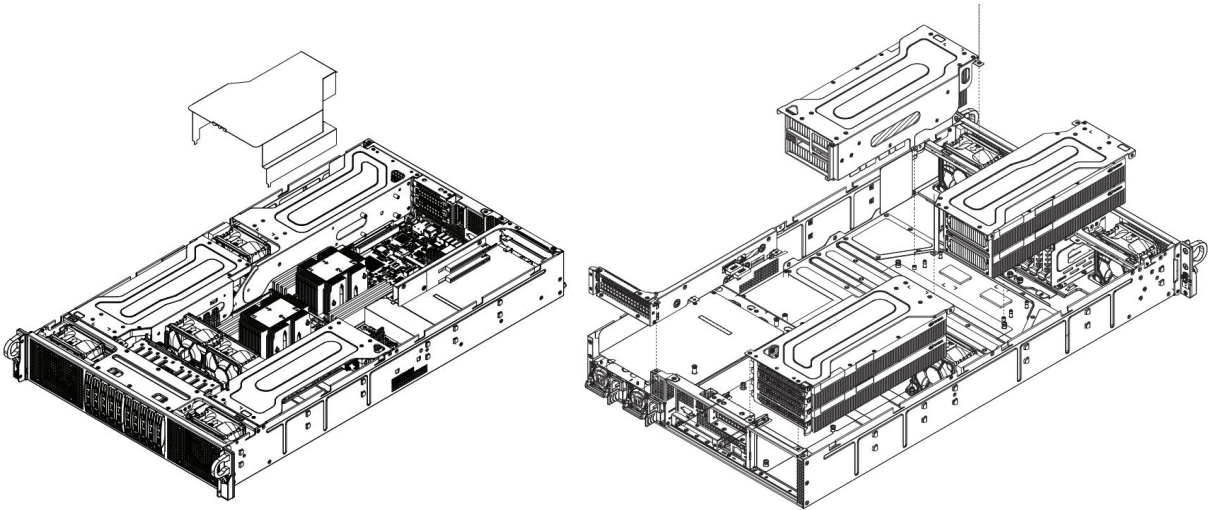
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## 4. Motherboard

*Type and number of fastenings:* Seven (7) PH2 screws.

*Tools required:* Screwdriver with PH2 bit.

*Procedure:* Remove the air shroud covering both CPUs, as well as the front-left, front-right, and rear expansion card brackets. Unfasten the screws securing the motherboard to the chassis, detach the power distribution board, then lift to remove.



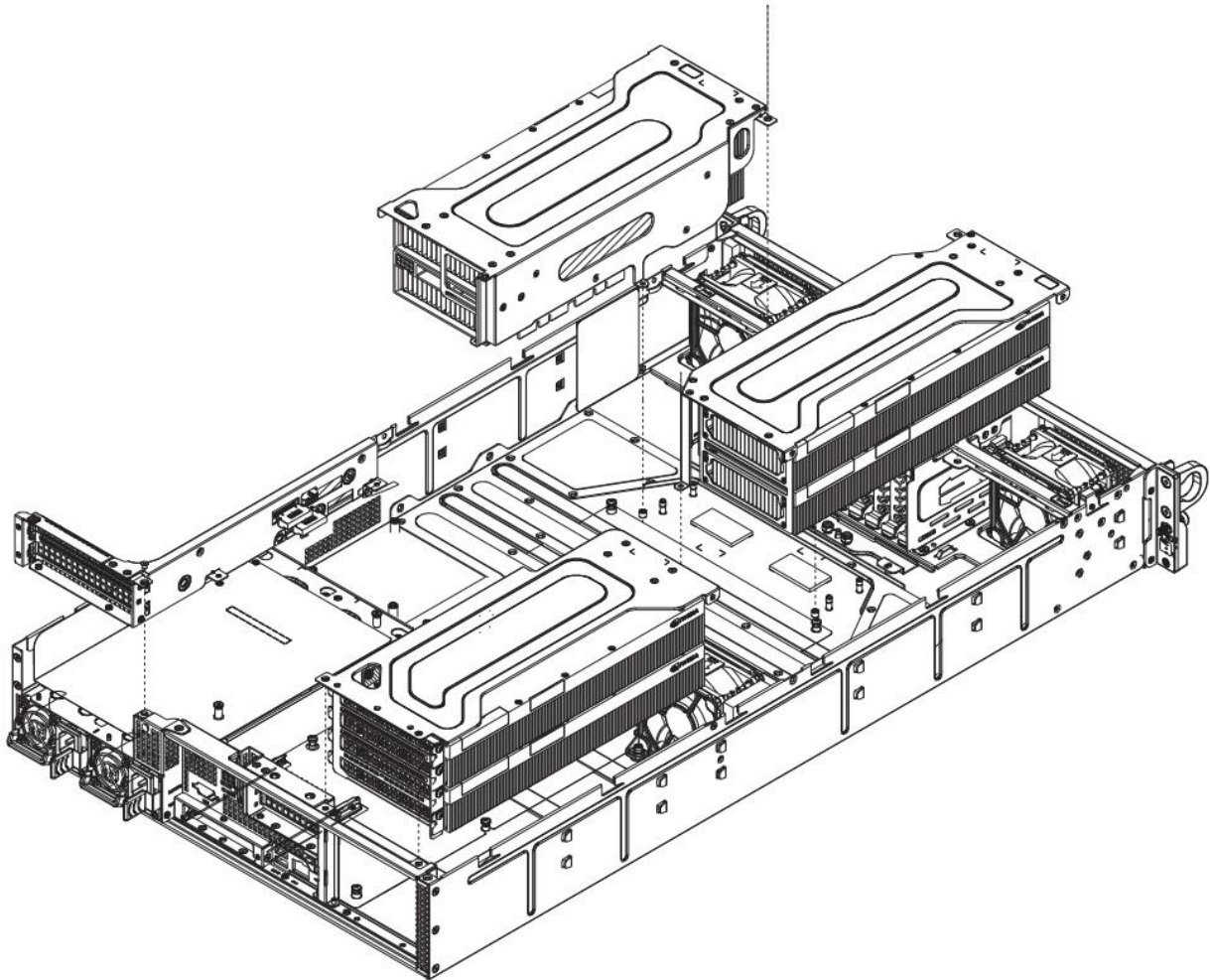
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## 5. Expansion Card/Graphics Card

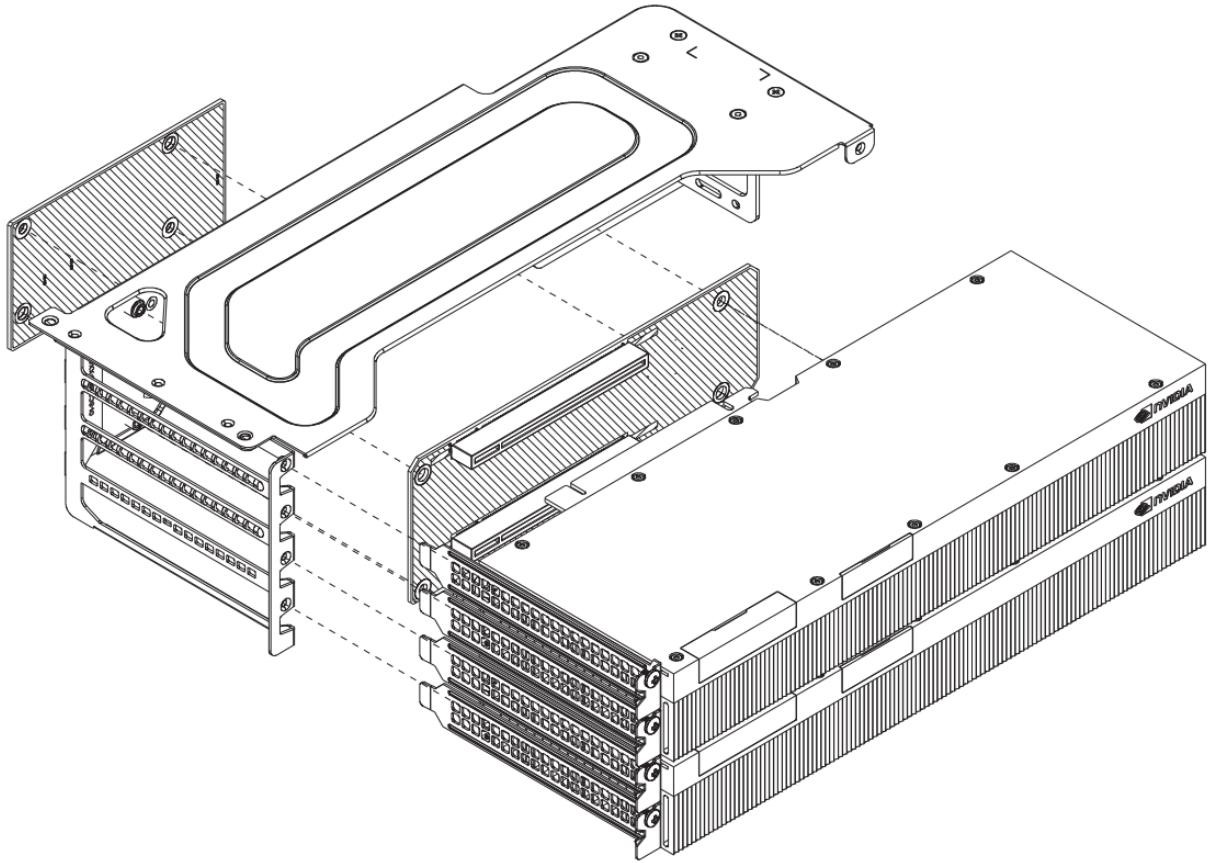
*Type and number of fastenings:* 19 PH2 screws.

*Tools required:* Screwdriver with PH2 bit.

*Procedure:* Remove the screws securing each expansion card bracket to the main chassis to detach them.



Remove the screws securing the expansion cards to each bracket, then remove them from their respective riser cards.



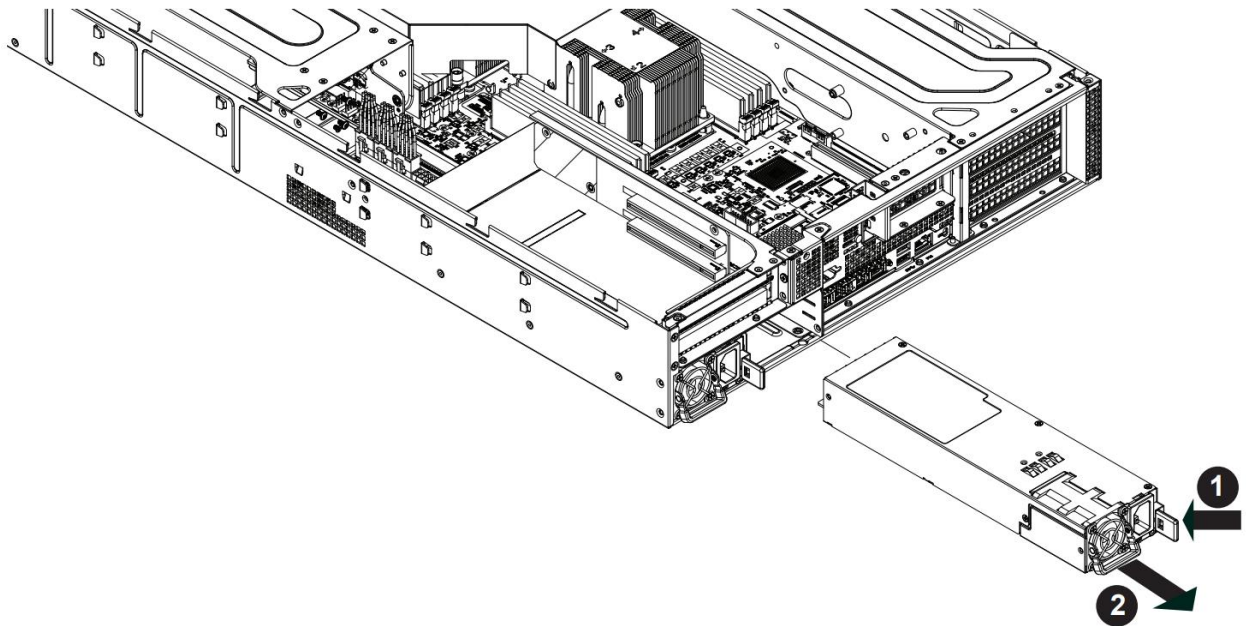
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## 6. Power Supply Module

*Type and number of fastenings:* One (1) latch per module.

*Tools required:* None.

*Procedure:* Squeeze the release tab on the back of the power supply module (1, below) toward the power socket, then pull the module straight out using the handle (2).



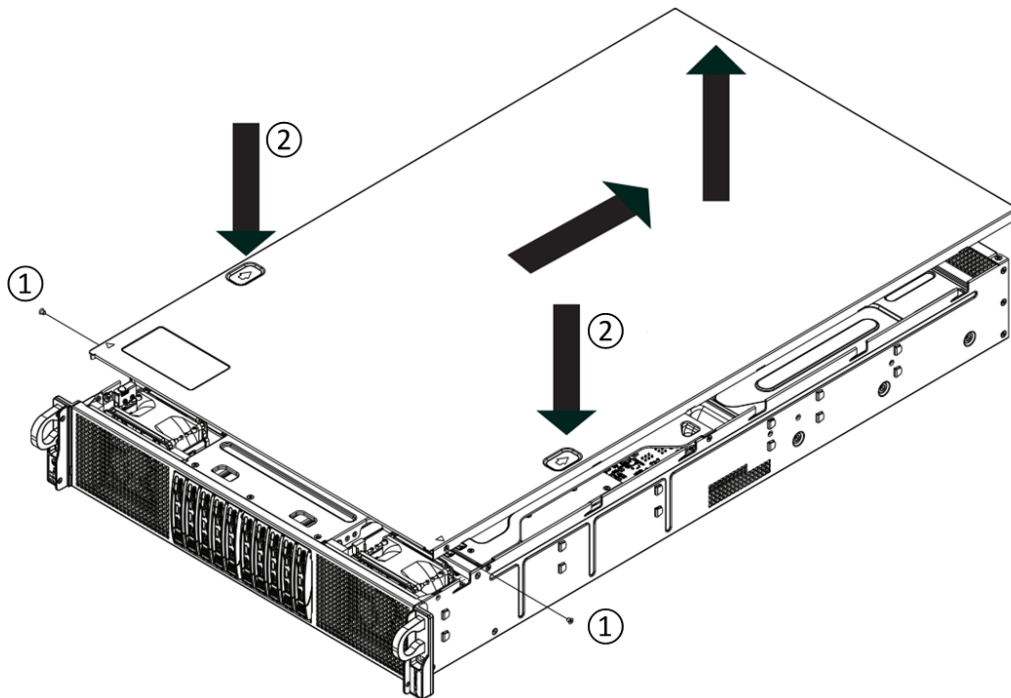
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## 7. Chassis Cover

Type and number of fastenings: Two (2) PH2 screws.

Tools required: Screwdriver with PH2 bit.

Procedure: Unfasten the screws on each side (1), as illustrated below. Apply downward force on the chassis cover (2), then slide the cover toward the rear of the system. Lift up to remove.



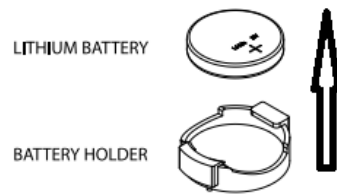
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## 8. Batteries

Type and number of fastenings: One (1) latch.

Tools required: None.

Procedure: Push aside the small clamp that covers the edge of the battery. When the battery is released, lift it out of the holder.



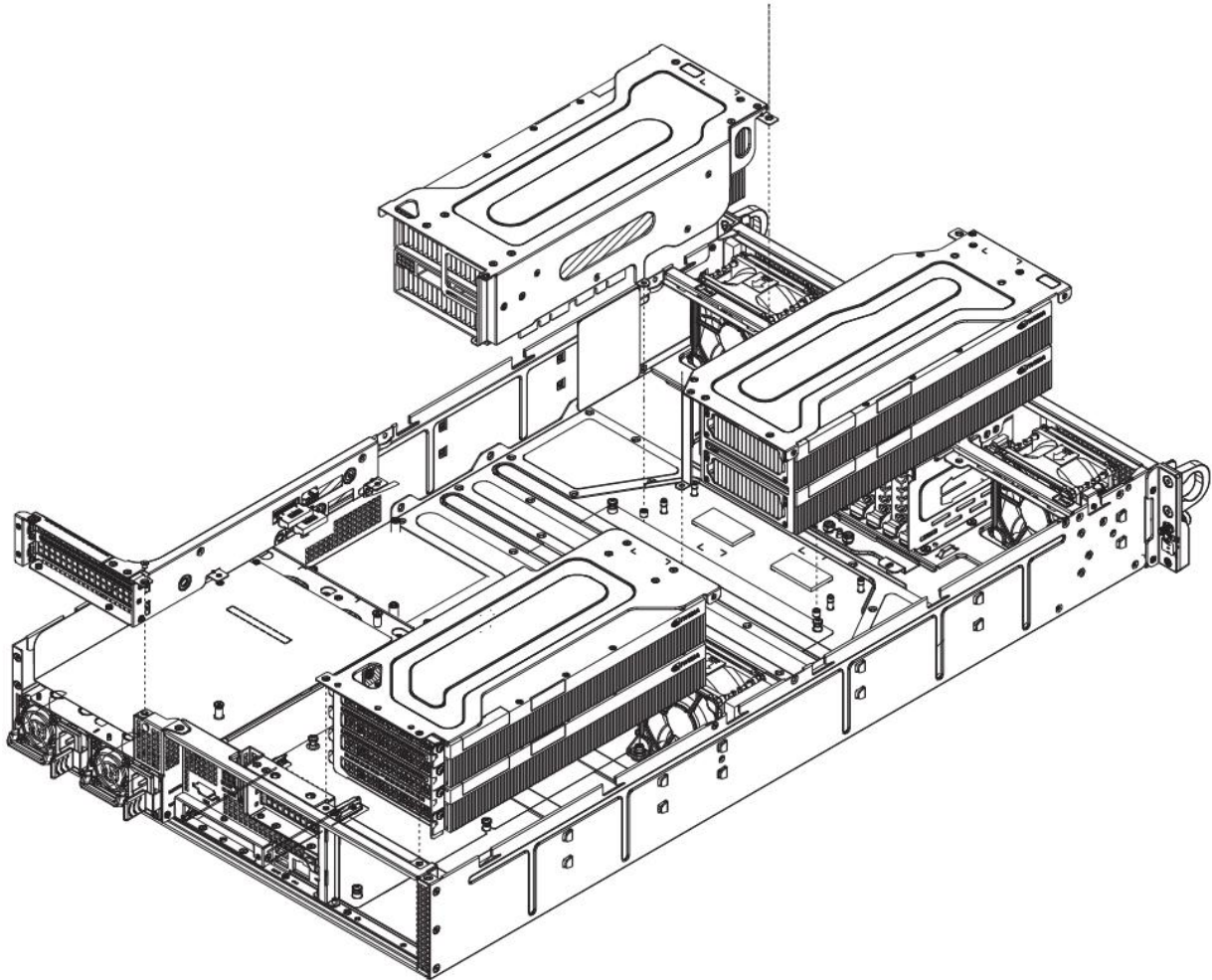
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## 9. Riser Card

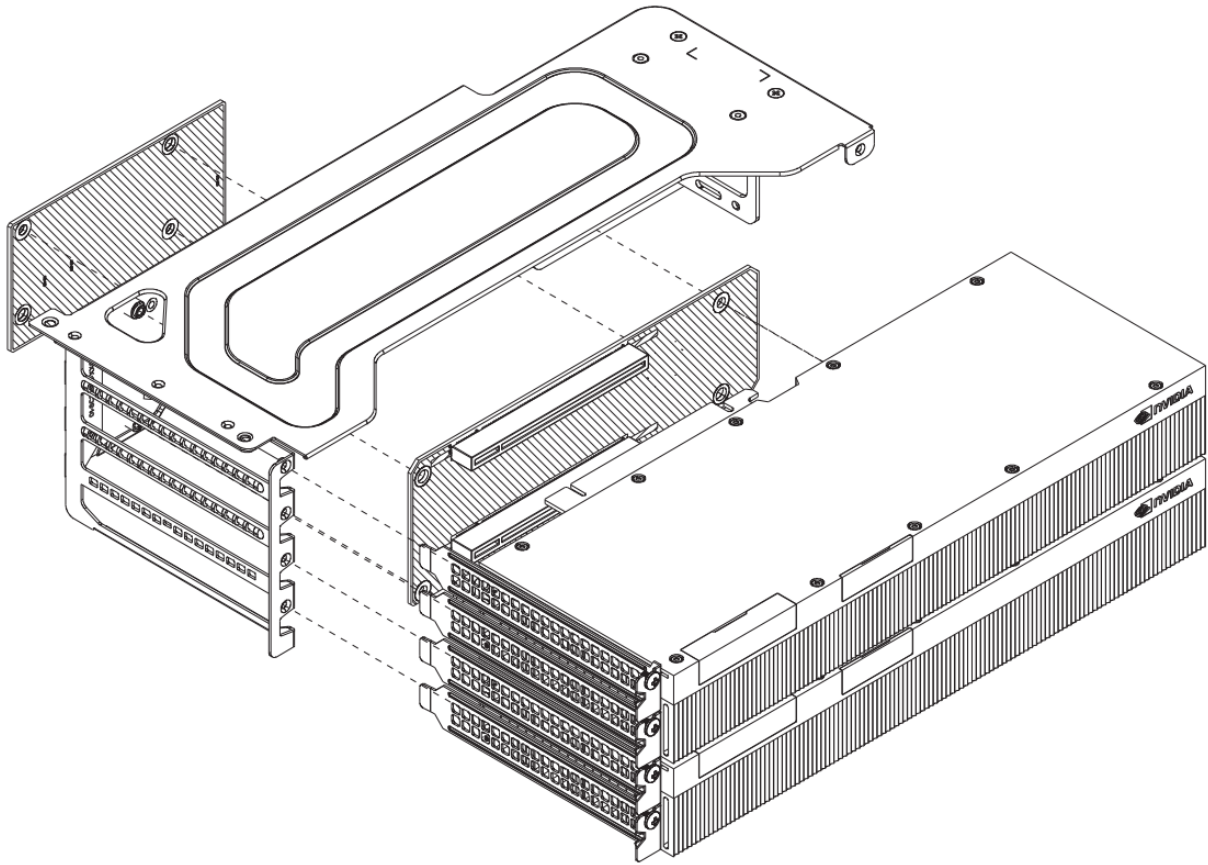
*Type and number of fastenings:* Four (4) PH2 screws each for RSC-G2B-66G4, RSC-G2F-66G4, RSC-G2FR-66G4, and RSC-G2R-8G4. Three (3) PH2 screws for RSC-G-88G4.

*Tools required:* Screwdriver with PH2 bit.

*Procedure:* Remove each expansion slot bracket from the main chassis, as illustrated below.



Remove any expansion cards occupying the riser cards, then unfasten the riser cards from their respective brackets.



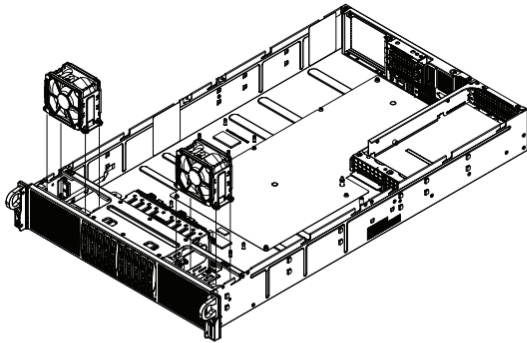
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## 10. Fans

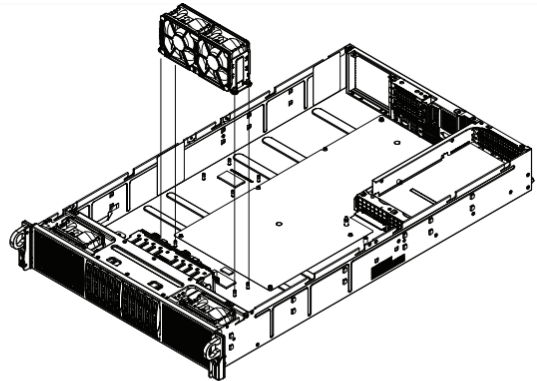
*Type and number of fastenings:* One (1) fan header per fan.

*Tools required:* None.

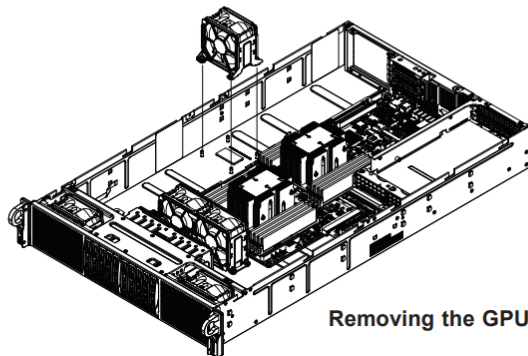
*Procedure:* Disconnect the fan wiring from the fan header on the motherboard, then remove fans from the main chassis.



Removing the Front Fans



Removing the Mid Fans



Removing the GPU Fan